



Aries Land Grid Array Socket, 16x16 Grid, 256 Pin, [.050] 1.27 Pitch

FEATURES:

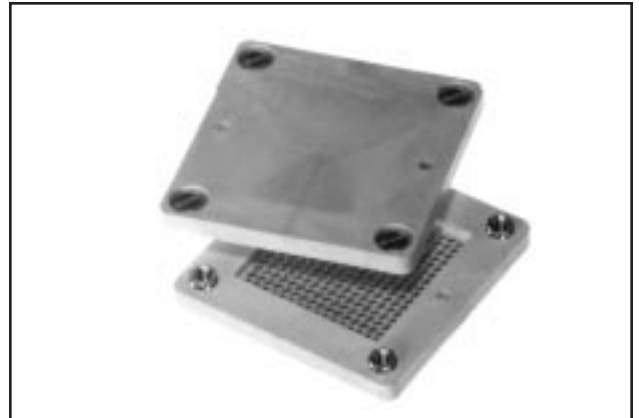
- Uses same surface mount soldering technology as BGA devices.
- LGA device is accurately aligned and seated in socket base prior to mounting of top.
- Controlled contact deflection.
- Simple mounting hardware requiring standard tools.
- Integral blind surface mount inserts in the base solder to top side of PCB and intergral flanged threaded inserts provide ample mounting pressure on device to eliminate need for backing plate on bottom side of PCB. Also reduces strain on solder ball terminations.
- Open window or metal top for heat sink application available as a special feature.

SPECIFICATIONS:

- Base and lid are UL 94V-0 glass filled LCP; color=natural.
- Contacts are heat treated Beryllium Copper Alloy per QQ-C-533.
- Contact plating is 30µ [.76µm] min. Gold per MIL-G-45204 over 30-50µ [.76-1.27µm] min. Nickel per QQ-N-290.
- Solder ball terminations are 90/10 Lead/Tin.
- Solder paste is 63/37 eutectic.
- Solder mask is "dryfilm."
- Hardware consists of Tin/Nickel plated blind & #2-56 threaded inserts and stainless steel slotted screws.
- Self inductance=1.50nH/contact @ 100MHz per EIA 364, Test Proc. 69.
- Capacitance=<1pF/contact @ 100MHz per EIA 364, Test Proc. 30.
- Contact Resistance=20mOhms max.
- Durability=20 cycles min.
- Contact Normal Force=40-50 grams/contact @ .008-.010" deflection.
- Currently under qualification testing per EIA/IS-701 and IBM's LGA Certification requirements specification, Version 5.0.

MOUNTING CONSIDERATIONS:

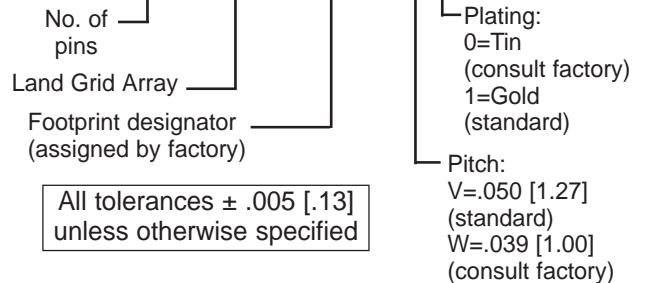
- See suggested PCB layout below.



Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

ORDERING INFORMATION

XXX-LGAXXXX-XX

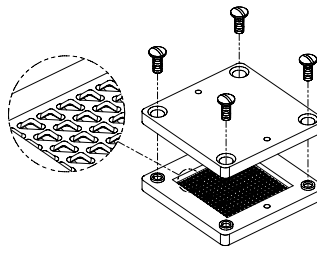
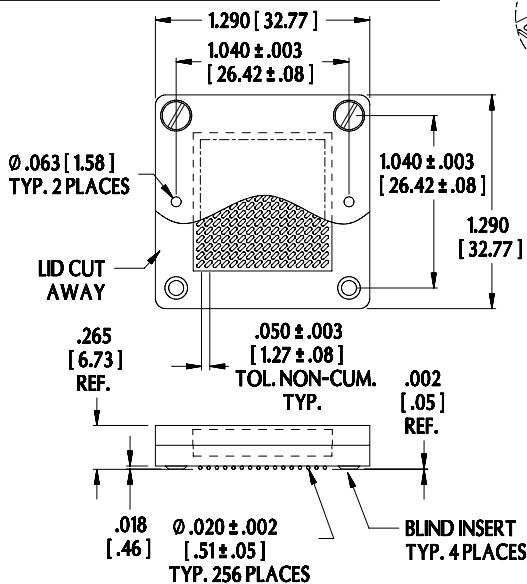


All tolerances ± .005 [.13] unless otherwise specified

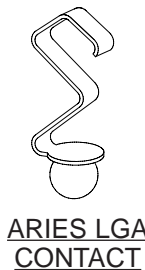
Consult factory for details.

Note: 256-LGA16001-V1 depicted here.

ALL DIMENSIONS: INCHES [MILLIMETERS]



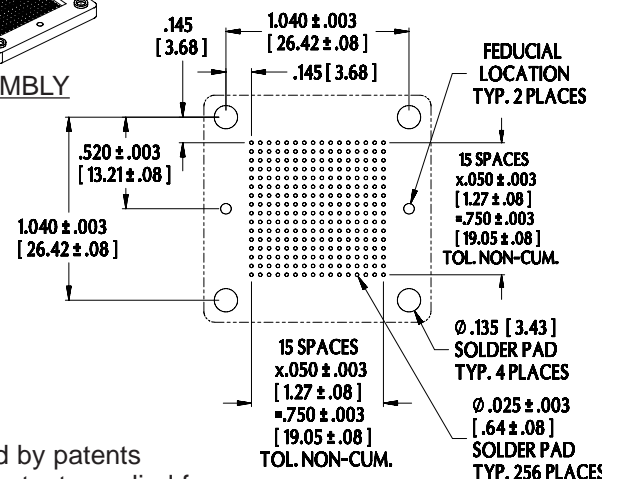
ASSEMBLY



ARIES LGA CONTACT

Covered by patents and/or patents applied for.

SUGGESTED PCB LAYOUT



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